

# Marked UP Claims

9. The manufacturing process for a printed wiring board according to (any of) claims 5 (to 8), characterized in that said  
10 organic layer is formed with one or two selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids.

10. The manufacturing process for a printed wiring board  
15 according to (any of) claims 5 (to 8), characterized in that said organic layer is formed by repeatedly applying an organic agent constituted of one or constituted as a mixture of two or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic  
20 compounds and carboxylic acids several times.

11. The manufacturing process for a printed wiring board according to (any of) claims 5 (to 8), characterized in that said  
25 organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several times.